

Abstract

A method for cutting an object (60), the object (60) including: a substrate (63) with an element mounted thereon; and a protective film (67) bonded to the substrate (63) to protect the element, includes: supplying a fluid from a fluid discharger (34) onto the
5 protective film (67) to cool the protective film (67); subsequently cutting the protective film (67); and subsequently cutting the substrate (63) while supplying cutting water onto the object (60), the cutting water having a temperature higher than a temperature of the fluid.

10 [Fig. 4B]